

Technical Data Sheet TOP View LEDs

67-21/YSC-FT1V1B/2T

Features

- P-LCC-2 package.
- White package.
- Optical indicator.
- Colorless clear window.
- Wide viewing angle.
- Suitable for vapor-phase reflow, Infrared reflow and wave solder processes.
- Computable with automatic placement equipment.
- Available on tape and reel (8mm Tape).
- Pb-free.
- The product itself will remain within RoHS compliant version.

Descriptions

• The 67-21 series is available in soft orange, green, blue and yellow. Due to the package design, the LED has wide viewing angle and optimized light coupling by inter reflector. This feature makes the ideal for light pipe application. The low current requirement makes this device ideal for portable equipment or any other application where power is at a premium.

Applications

- Automotive: backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in telephone and fax.
- Flat backlight for LCD, switch and symbol.
- Light pipe application.
- General use.

Device Selection Guide

	Lens Color	
Material Emitted Color		
AlGaInP	Brilliant Yellow	Water Clear

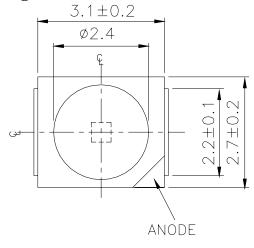


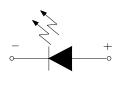
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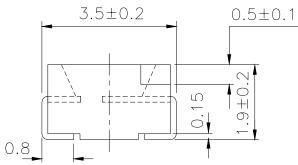
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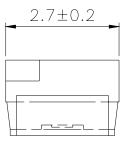
Package Dimensions



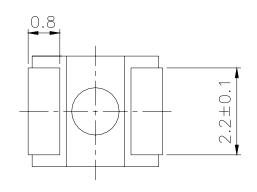


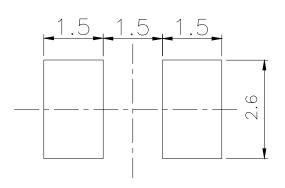
Polarity





For reflow soldering (Proposal)





Note: The tolerances unless mentioned is ± 0.1 mm ,Unit = mm This is N-TOP chip

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Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Units
Reverse Voltage	VR	5	V
Forward Current	IF	50	mA
Operating Temperature	Topr	-40 ~ +85	$^{\circ}\!\mathbb{C}$
Storage Temperature	Tstg	-40 ~ +100	$^{\circ}\!\mathbb{C}$
Electrostatic Discharge(HBM)	ESD	2000	V
Power Dissipation	Pd	120	mW
Peak Forward Current (Duty 1/10 @1KHz)	IFP	100	mA
Soldering Temperature	Tsol	Reflow Soldering: 260 °C for 10 sec. Hand Soldering: 350 °C for 3 sec.	

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Luminous intensity	IV	285		900	mcd	IF=20mA
Viewing Angle	2 θ 1/2		120		deg	IF=20mA
Peak Wavelength	λp		591		nm	IF=20mA
Dominant Wavelength	λd	586		594	nm	IF=20mA
Spectrum Radiation Bandwidth	Δλ		20		nm	IF=20mA
Forward Voltage	VF	1.75		2.35	V	IF=20mA
Reverse Current	IR			10	μΑ	VR=5V

Notes:

- 1.Tolerance of Luminous Intensity ±10%
- 2.Tolerance of Dominant Wavelength ±1nm
- 3.Tolerance of Forward Voltage ±0.1V

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Bin Range Of Dominant Wavelength

Group	Bin Code	Min.	Max.	Unit	Condition
F	DD1	586	588		I _F =20mA
	DD2	588	590		
	DD3	590	592	nm	
	DD4	592	594		

Bin Range Of Luminous Intensity

Bin	Min	Max	Unit	Condition
T1	285	360		
T2	360	450		
U1	450	565	mcd	IF=20mA
U2	565	715		
V1	715	900		

Bin Range Of Forward Voltage

Group	Bin	Min	Max	Unit	Condition	
	0	1.75	1.95			
В	1	1.95	2.15	V	IF=20mA	
	2	2.15	2.35			

Notes:

- 1.Tolerance of Luminous Intensity ±10%
- 2.Tolerance of Dominant Wavelength ±1nm
- 3.Tolerance of Forward Voltage ±0.1V

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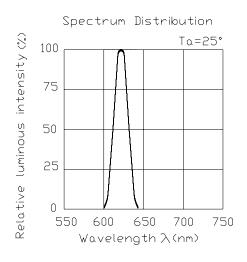
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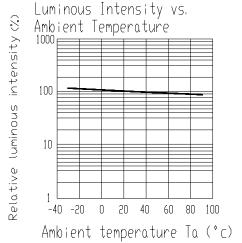
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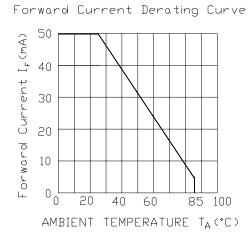
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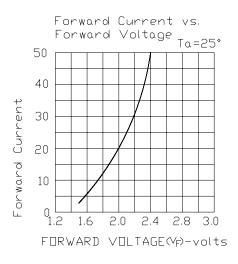
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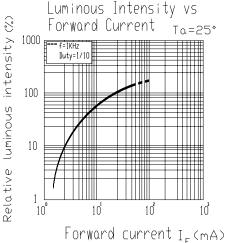
Typical Electro-Optical Characteristics Curves

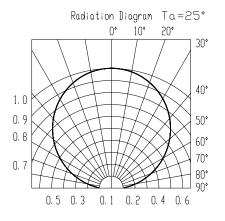












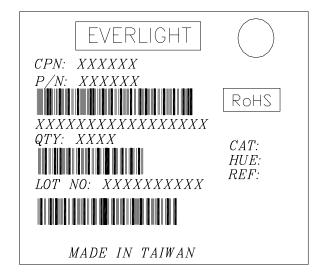
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Label explanation

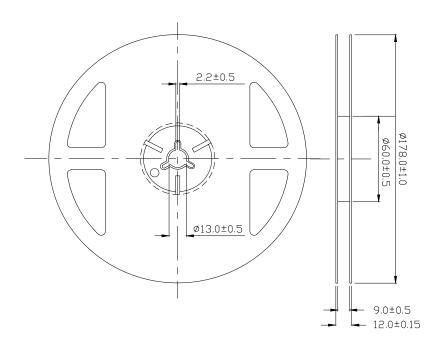
CAT: Luminous Intensity Rank

HUE: Dom. Wavelength Rank

REF: Forward Voltage Rank



Reel Dimensions

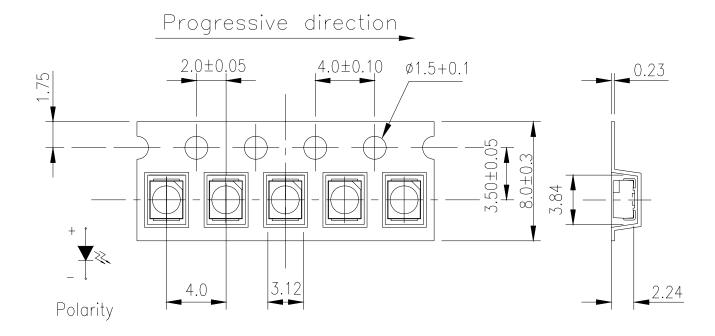


Note: The tolerances unless mentioned is ± 0.1 mm, Unit = mm



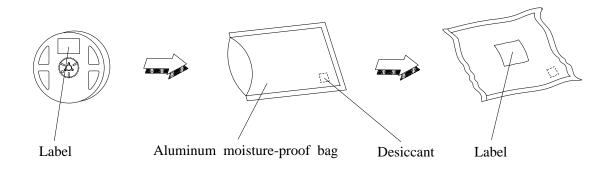
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Carrier Tape Dimensions: Loaded quantity 2000 PCS per reel.



Note: The tolerances unless mentioned is ± 0.1 mm Unit = mm

Moisture Resistant Packaging



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Reliability Test Items And Conditions

The reliability of products shall be satisfied with items listed below.

Confidence level: 90%

LTPD: 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260°C±5°C Min. 5sec.	6 min	22 PCS.	0/1
2	Temperature Cycle	H:+100°C 15min ∫ 5 min L:-40°C 15min	300 Cycles	22 PCS.	0/1
3	Thermal Shock	$H: +100^{\circ}\mathbb{C}$ 5min $\int 10 \sec$ $L: -10^{\circ}\mathbb{C}$ 5min	300 Cycles	22 PCS.	0/1
4	High Temperature Storage	Temp. : 100°C	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Temp. : -40°C	1000 Hrs.	22 PCS.	0/1
6	DC Operating Life	If = $20 \text{ mA}/25^{\circ}\text{C}$	1000 Hrs.	22 PCS.	0/1
7	High Temperature / High Humidity	85°C / 85%RH	1000 Hrs.	22 PCS.	0/1

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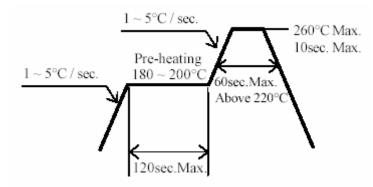
Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

- 2. Storage
 - 2.1 Do not open moisture proof bag before the products are ready to use.
 - 2.2 Before opening the package: The LEDs should be kept at 30° C or less and 90%RH or less.
 - 2.3 After opening the package: The LED's floor life is 1 year under 30 deg C or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.
 - 2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

 Baking treatment: 60±5°C for 24 hours.
- 3. Soldering Condition
- 3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.
- 4.Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350° C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

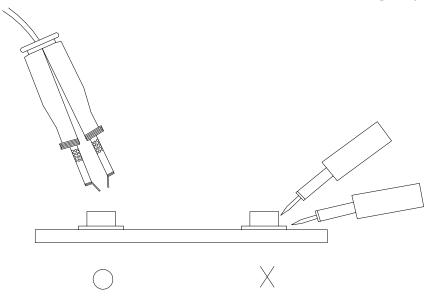
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5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



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